

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph beginning at page 13, line 8 as shown below (Note the following amendments are further to the preliminary amendment originally filed on January 23, 2001):

“The vertically-connected stripline structure described herein comprises a stack of substrate layers. A substrate “layer” is defined as a substrate including circuitry on one or both sides. A process for constructing such a multilayer structure is disclosed by U.S. Patent Application No. 09/199,675 entitled “Method of Making Microwave Multifunction Modules Using Fluoropolymer Composite Substrates, filed November 25, 1998, now U.S. Patent No. [6,099,977]6,099,677 to Logothetis et al., incorporated herein by reference. Not that references to “substrate layer” and “metal layer” herein are often referred to as “layer” and “metallization”, respectively, in U.S. Patent No. [6,099,977]6,099,677.”